



August 2015

FDMS8095AC

Dual N & P-Channel PowerTrench® MOSFET

N-Channel: 150 V, 27 A, 30 mΩ P-Channel: -150 V, -2.2 A, 1200 mΩ

Features

Q1: N-Channel

- Max $r_{DS(on)}$ = 30 mΩ at $V_{GS} = 10$ V, $I_D = 6.2$ A
- Max $r_{DS(on)}$ = 41 mΩ at $V_{GS} = 6$ V, $I_D = 5.2$ A

Q2: P-Channel

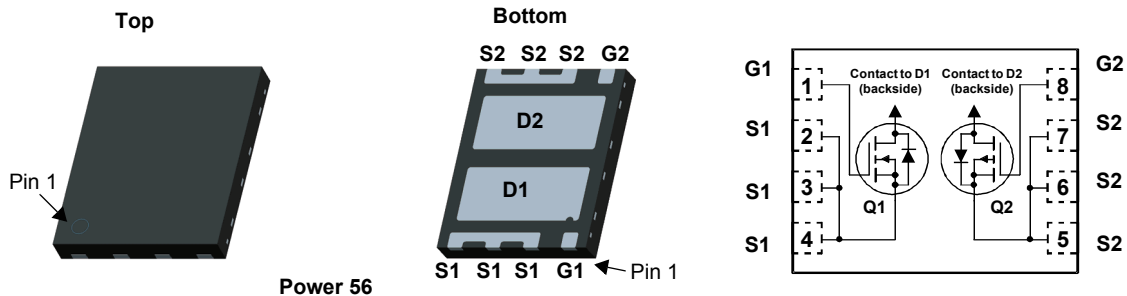
- Max $r_{DS(on)}$ = 1200 mΩ at $V_{GS} = -10$ V, $I_D = -1$ A
- Max $r_{DS(on)}$ = 1400 mΩ at $V_{GS} = -6$ V, $I_D = -0.9$ A
- Optimised for active clamp forward converters
- RoHS Compliant

General Description

These dual N and P-Channel enhancement mode Power MOSFETs are produced using Fairchild Semiconductor's advanced PowerTrench® process that has been especially tailored to minimize on-state resistance and yet maintain superior switching performance. Shrinking the area needed for implementation of active clamp topology; enabling best in class power density.

Applications

- DC-DC Converter
- Active Clamp



MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Q1 | Q2 | Units |
|----------------|---|-------------------|-------------------|------------------|
| V_{DS} | Drain to Source Voltage | 150 | -150 | V |
| V_{GS} | Gate to Source Voltage | ± 20 | ± 25 | V |
| I_D | Drain Current -Continuous $T_C = 25^\circ\text{C}$ (Note 5) | 27 | -2.2 | A |
| | Drain Current -Continuous $T_C = 100^\circ\text{C}$ (Note 5) | 17 | -1.4 | |
| | -Continuous $T_A = 25^\circ\text{C}$ | 6.2 ^{1a} | -1 ^{1b} | |
| | -Pulsed (Note 4) | 143 | -8.8 | |
| E_{AS} | Single Pulse Avalanche Energy (Note 3) | 216 | 6 | mJ |
| P_D | Power Dissipation for Single Operation $T_A = 25^\circ\text{C}$ | 2.3 ^{1a} | 2.3 ^{1b} | W |
| | Power Dissipation for Single Operation $T_A = 25^\circ\text{C}$ | 0.9 ^{1c} | 0.9 ^{1d} | |
| | Power Dissipation for Single Operation $T_C = 25^\circ\text{C}$ | 50 | 12.5 | |
| T_J, T_{STG} | Operating and Storage Junction Temperature Range | -55 to +150 | | $^\circ\text{C}$ |

Thermal Characteristics

| | | | | |
|-----------------|---|-------------------|-------------------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 55 ^{1a} | 55 ^{1b} | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 138 ^{1c} | 138 ^{1d} | |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 2.5 | 10 | |

Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|------------|----------|-----------|------------|------------|
| FDMS8095AC | FDMS8095AC | Power 56 | 13" | 12 mm | 3000 units |

Electrical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Type | Min | Typ | Max | Units |
|--------|-----------|-----------------|------|-----|-----|-----|-------|
|--------|-----------|-----------------|------|-----|-----|-----|-------|

Off Characteristics

| | | | | | | | |
|--------------------------------------|---|---|----------|-------------|------------|------------------------|----------------------|
| BV_{DSS} | Drain to Source Breakdown Voltage | $I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0\text{ V}$ $I_D = -250\text{ }\mu\text{A}$, $V_{GS} = 0\text{ V}$ | Q1 Q2 | 150 -150 | | | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature Coefficient | $I_D = 250\text{ }\mu\text{A}$, referenced to $25\text{ }^\circ\text{C}$ $I_D = -250\text{ }\mu\text{A}$, referenced to $25\text{ }^\circ\text{C}$ | Q1 Q2 | | 103 122 | | mV/ $^\circ\text{C}$ |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 120\text{ V}$, $V_{GS} = 0\text{ V}$ $V_{DS} = -120\text{ V}$, $V_{GS} = 0\text{ V}$ | Q1 Q2 | | | 1 -1 | μA |
| I_{GSS} | Gate to Source Leakage Current | $V_{GS} = \pm 20\text{ V}$, $V_{DS} = 0\text{ V}$ $V_{GS} = \pm 25\text{ V}$, $V_{DS} = 0\text{ V}$ | Q1 Q2 | | | ± 100 ± 100 | nA |

On Characteristics

| | | | | | | | |
|--|--|--|----------|-------------|--------------------|----------------------|----------------------|
| $V_{GS(th)}$ | Gate to Source Threshold Voltage | $V_{GS} = V_{DS}$, $I_D = 250\text{ }\mu\text{A}$ $V_{GS} = V_{DS}$, $I_D = -250\text{ }\mu\text{A}$ | Q1 Q2 | 2.0 -2.0 | 3.2 -3.2 | 4.0 -4.0 | V |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate to Source Threshold Voltage Temperature Coefficient | $I_D = 250\text{ }\mu\text{A}$, referenced to $25\text{ }^\circ\text{C}$ $I_D = -250\text{ }\mu\text{A}$, referenced to $25\text{ }^\circ\text{C}$ | Q1 Q2 | | -11 -6 | | mV/ $^\circ\text{C}$ |
| $r_{DS(on)}$ | Static Drain to Source On Resistance | $V_{GS} = 10\text{ V}$, $I_D = 6.2\text{ A}$ $V_{GS} = 6\text{ V}$, $I_D = 5.2\text{ A}$ $V_{GS} = 10\text{ V}$, $I_D = 6.2\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$ | Q1 | | 25 33 48 | 30 41 58 | m Ω |
| | | $V_{GS} = -10\text{ V}$, $I_D = -1\text{ A}$ $V_{GS} = -6\text{ V}$, $I_D = -0.9\text{ A}$ $V_{GS} = -10\text{ V}$, $I_D = -1\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$ | Q2 | | 840 940 1520 | 1200 1400 2171 | |
| g_{FS} | Forward Transconductance | $V_{DD} = 10\text{ V}$, $I_D = 6.2\text{ A}$ $V_{DD} = -10\text{ V}$, $I_D = -1\text{ A}$ | Q1 Q2 | | 19 0.75 | | S |

Dynamic Characteristics

| | | | | | | | |
|------------|------------------------------|---|----|-----|------|------|----------|
| C_{iss} | Input Capacitance | Q1 $V_{DS} = 75\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$ | Q1 | | 1441 | 2020 | pF |
| | | | Q2 | | 162 | 230 | |
| C_{oss} | Output Capacitance | Q2 | Q1 | | 127 | 180 | pF |
| | | | Q2 | | 13 | 25 | |
| C_{riss} | Reverse Transfer Capacitance | $V_{DS} = -75\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$ | Q1 | | 4.4 | 10 | pF |
| | | | Q2 | | 0.6 | 5 | |
| R_g | Gate Resistance | | Q1 | 0.1 | 1.3 | 3.3 | Ω |
| | | | Q2 | 0.1 | 3.3 | 8.3 | |

Switching Characteristics

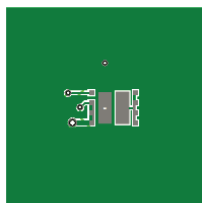
| | | | | | | | |
|--------------|-------------------------------|--|----------|--|------------|----------|----|
| $t_{d(on)}$ | Turn-On Delay Time | Q1 $V_{DD} = 75\text{ V}$, $I_D = 6.2\text{ A}$, $V_{GS} = 10\text{ V}$, $R_{GEN} = 6\text{ }\Omega$ | Q1 Q2 | | 12 5.2 | 22 11 | ns |
| t_r | Rise Time | | Q1 Q2 | | 2.7 1.6 | 10 10 | |
| $t_{d(off)}$ | Turn-Off Delay Time | Q2 $V_{DD} = -75\text{ V}$, $I_D = -1\text{ A}$, $V_{GS} = -10\text{ V}$, $R_{GEN} = 6\text{ }\Omega$ | Q1 Q2 | | 18 7.4 | 33 15 | ns |
| t_f | Fall Time | | Q1 Q2 | | 4 6.3 | 10 13 | |
| $Q_{g(TOT)}$ | Total Gate Charge | $V_{GS} = 0\text{ V to }10\text{ V}$ $V_{GS} = 0\text{ V to }-10\text{ V}$ | Q1 Q2 | $V_{DD} = 75\text{ V}$, $I_D = 6.2\text{ A}$ | 21 | 30 | nC |
| | | | | | 2.8 | 4 | |
| $Q_{g(TOT)}$ | Total Gate Charge | $V_{GS} = 0\text{ V to }6\text{ V}$ $V_{GS} = 0\text{ V to }-6\text{ V}$ | Q1 Q2 | | 13 | 19 | nC |
| | | | | | 1.8 | 2.6 | |
| Q_{gs} | Gate to Source Charge | | Q1 Q2 | | 6.7 | | nC |
| | | | | | 0.8 | | |
| Q_{gd} | Gate to Drain "Miller" Charge | | Q1 Q2 | | 3.9 | | nC |
| | | | | | 0.7 | | |

Electrical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted

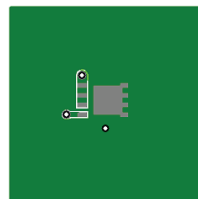
| Symbol | Parameter | Test Conditions | Type | Min | Typ | Max | Units |
|----------|------------------------------------|---|------|-----|------|------|-------|
| V_{SD} | Source-Drain Diode Forward Voltage | $V_{GS} = 0\text{ V}$, $I_S = 6.2\text{ A}$ (Note 2) | Q1 | | 0.8 | 1.3 | V |
| | | $V_{GS} = 0\text{ V}$, $I_S = -1\text{ A}$ (Note 2) | Q2 | | -0.9 | -1.3 | |
| t_{rr} | Reverse Recovery Time | Q1 $I_F = 6.2\text{ A}$, $di/dt = 100\text{ A/s}$ | Q1 | | 69 | 111 | ns |
| | | | Q2 | | 44 | 71 | |
| Q_{rr} | Reverse Recovery Charge | Q2 $I_F = -1\text{ A}$, $di/dt = 100\text{ A/s}$ | Q1 | | 106 | 170 | nC |
| | | | Q2 | | 68 | 109 | |

Notes:

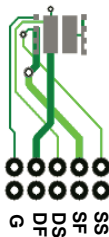
1. $R_{\theta JA}$ is determined with the device mounted on a 1 in^2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta CA}$ is determined by the user's board design.



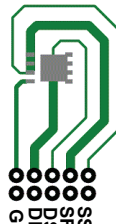
a. $55\text{ }^\circ\text{C/W}$ when mounted on a 1 in^2 pad of 2 oz copper



b. $55\text{ }^\circ\text{C/W}$ when mounted on a 1 in^2 pad of 2 oz copper



c. $138\text{ }^\circ\text{C/W}$ when mounted on a minimum pad of 2 oz copper



d. $138\text{ }^\circ\text{C/W}$ when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width < 300 μs , Duty cycle < 2.0%.

3. Q1: E_{AS} of 216 mJ is based on starting $T_J = 25\text{ }^\circ\text{C}$, $L = 3\text{ mH}$, $I_{AS} = 12\text{ A}$, $V_{DD} = 150\text{ V}$, $V_{GS} = 10\text{ V}$. 100% test at $L = 0.3\text{ mH}$, $I_{AS} = 28\text{ A}$.

Q2: E_{AS} of 6 mJ is based on starting $T_J = 25\text{ }^\circ\text{C}$, $L = 3\text{ mH}$, $I_{AS} = -2\text{ A}$, $V_{DD} = -150\text{ V}$, $V_{GS} = -10\text{ V}$. 100% test at $L = 0.3\text{ mH}$, $I_{AS} = -6.9\text{ A}$.

4. Pulsed I_d please refer to Fig 11 SOA graph for more details.

5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

Typical Characteristics (Q1 N-Channel) $T_J = 25^\circ\text{C}$ unless otherwise noted

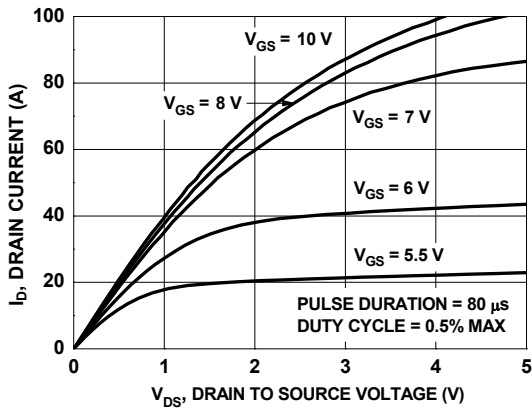


Figure 1. On Region Characteristics

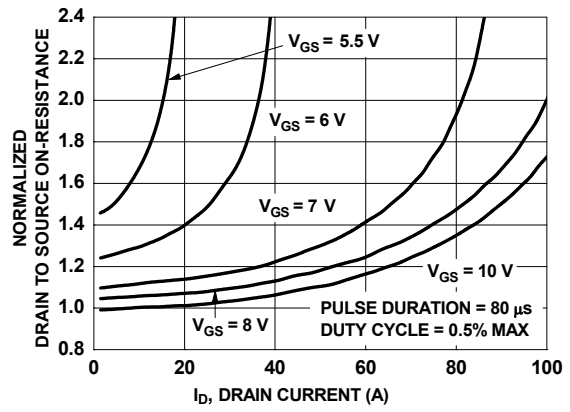


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

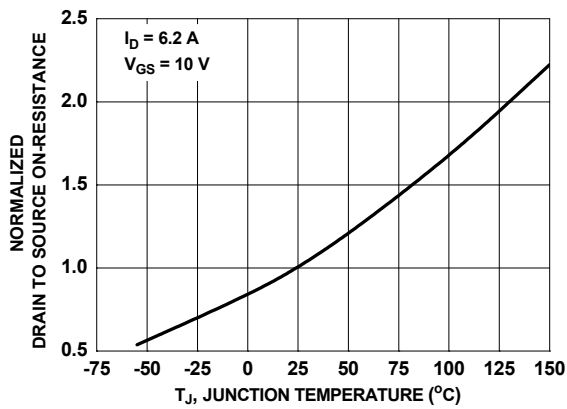


Figure 3. Normalized On Resistance vs Junction Temperature

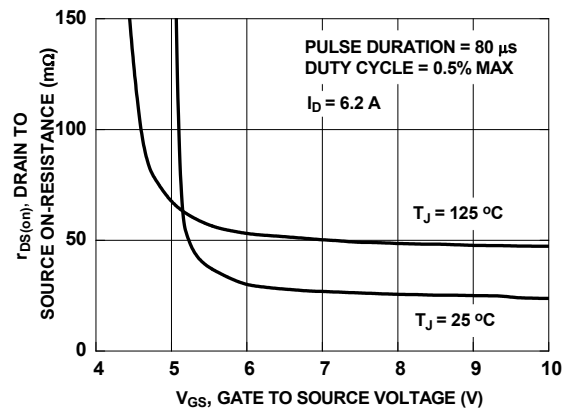


Figure 4. On-Resistance vs Gate to Source Voltage

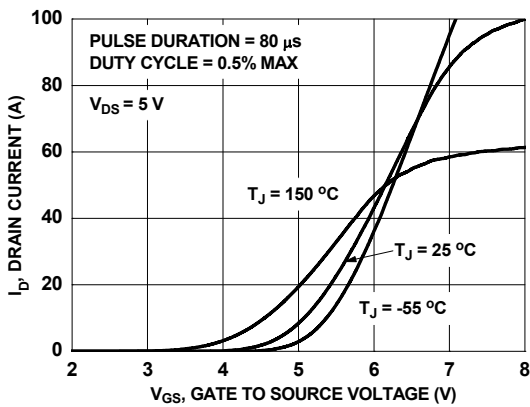


Figure 5. Transfer Characteristics

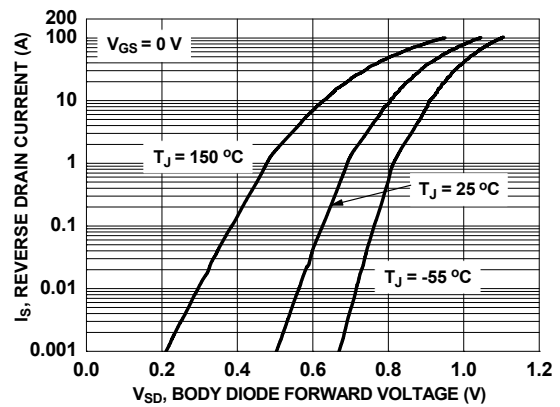


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics (Q1 N-Channel) $T_J = 25^\circ\text{C}$ unless otherwise noted

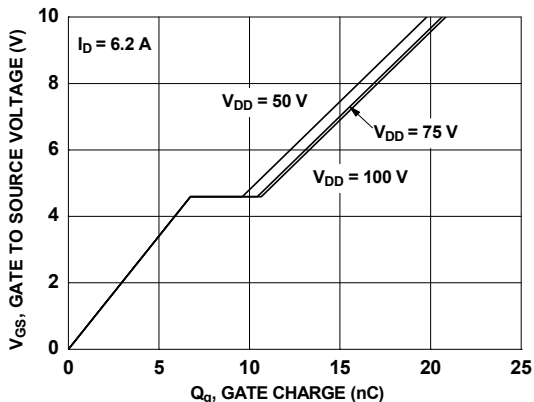


Figure 7. Gate Charge Characteristics

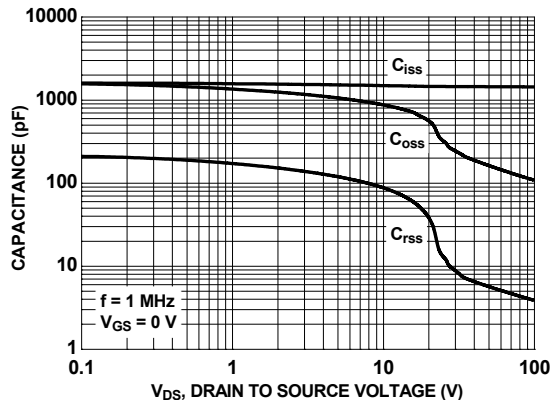


Figure 8. Capacitance vs Drain to Source Voltage

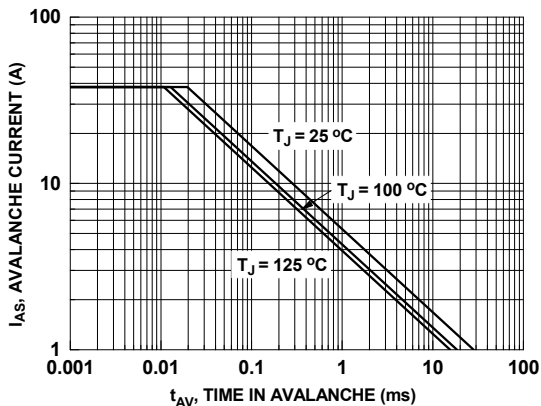


Figure 9. Unclamped Inductive Switching Capability

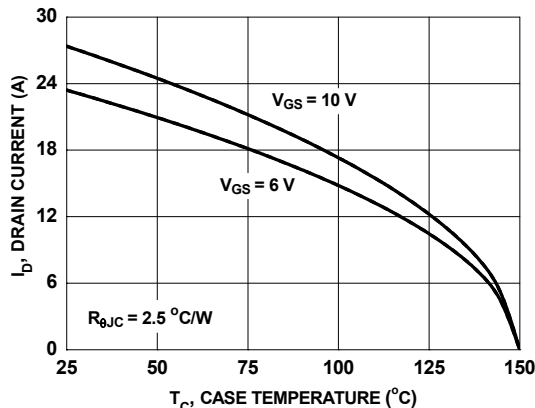


Figure 10. Maximum Continuous Drain Current vs Case Temperature

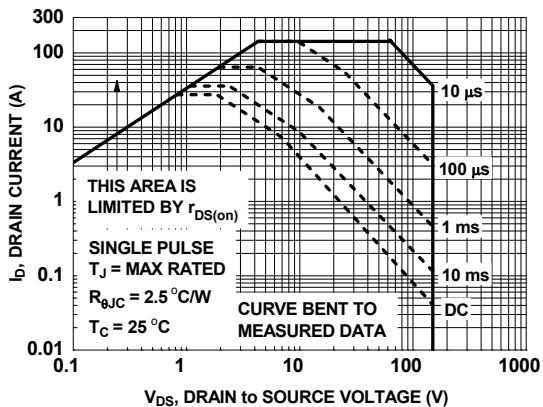


Figure 11. Forward Bias Safe Operating Area

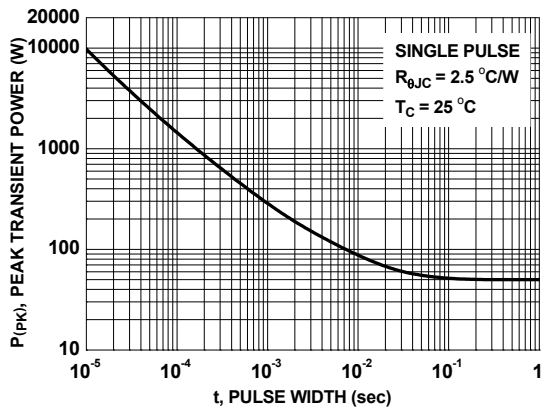


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics (Q1 N-Channel) $T_J = 25^\circ\text{C}$ unless otherwise noted

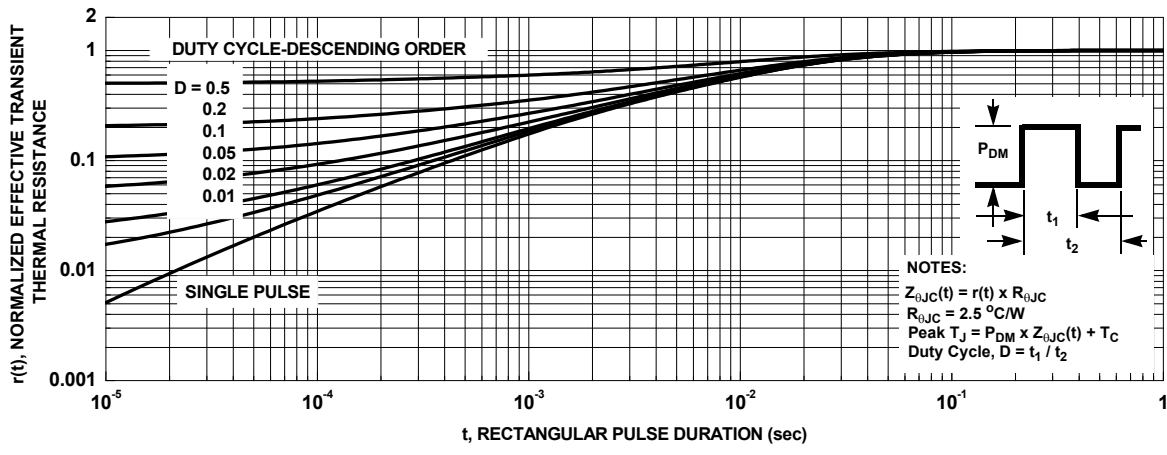


Figure 13. Junction-to-Case Transient Thermal Response Curve

Typical Characteristics (Q2 P-Channel) $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted

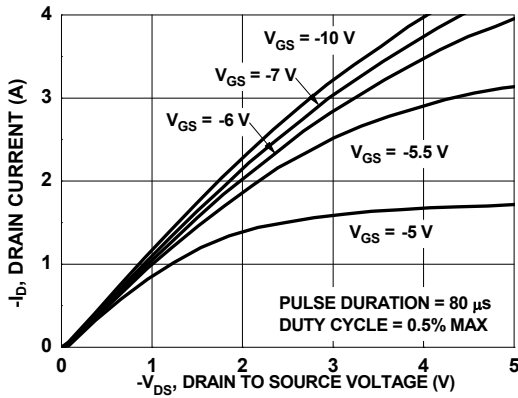


Figure 14. On-Region Characteristics

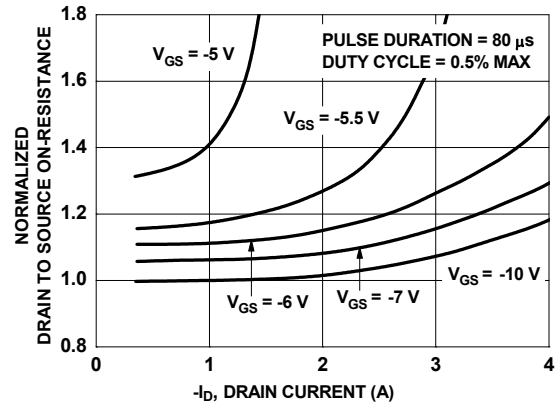


Figure 15. Normalized on-Resistance vs Drain Current and Gate Voltage

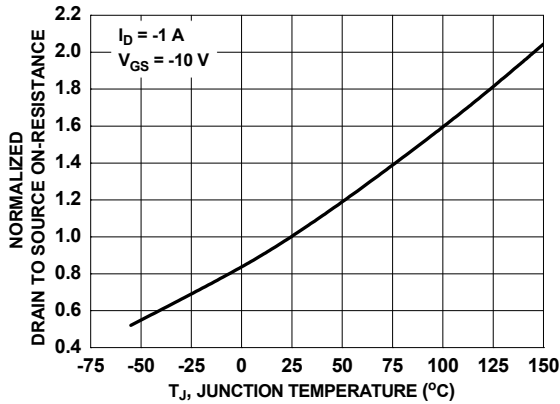


Figure 16. Normalized On-Resistance vs Junction Temperature

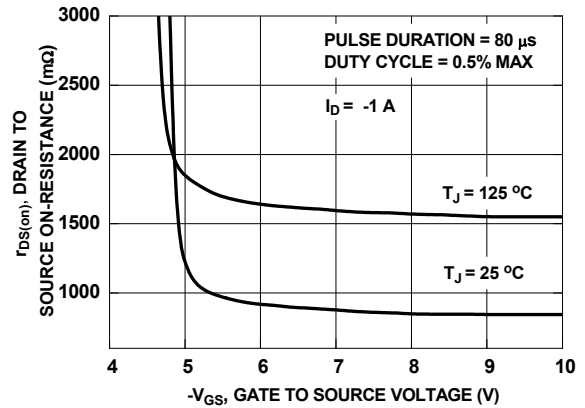


Figure 17. On-Resistance vs Gate to Source Voltage

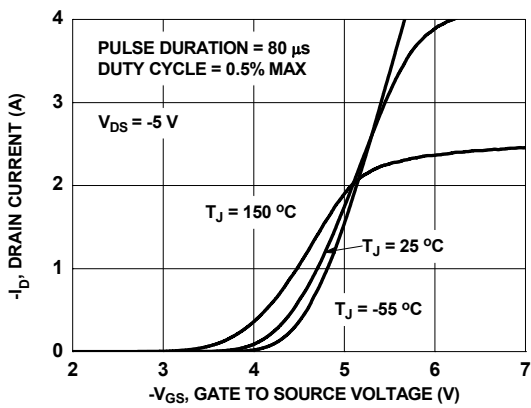


Figure 18. Transfer Characteristics

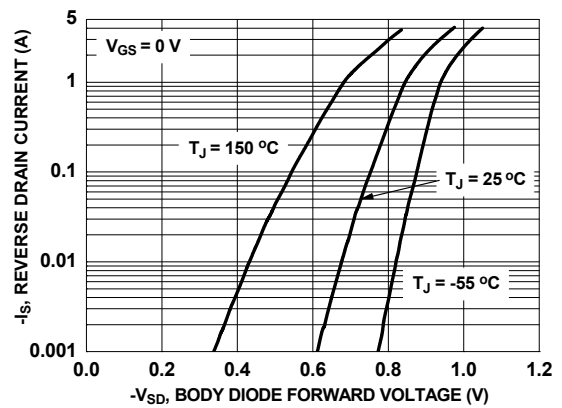


Figure 19. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics (Q2 P-Channel) $T_J = 25^\circ\text{C}$ unless otherwise noted

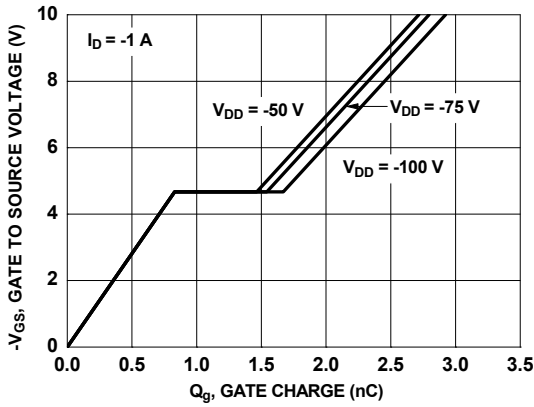


Figure 20. Gate Charge Characteristics

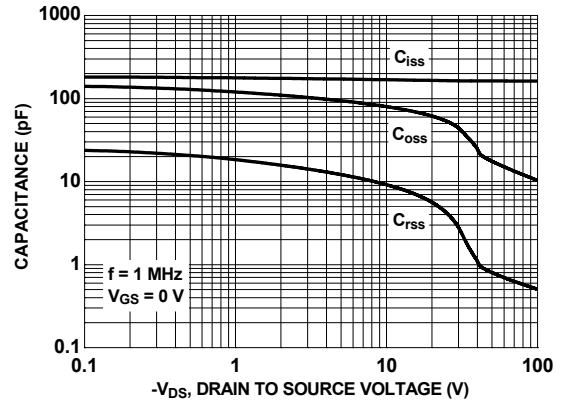


Figure 21. Capacitance vs Drain to Source Voltage

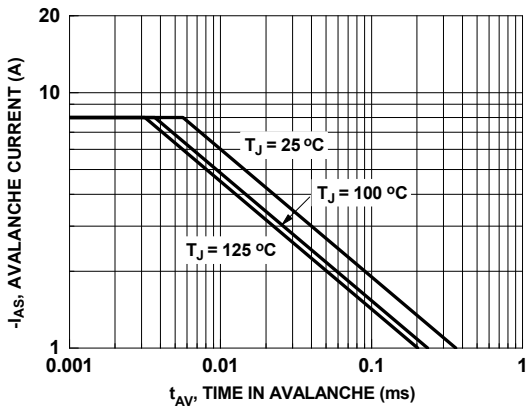


Figure 22. Unclamped Inductive Switching Capability

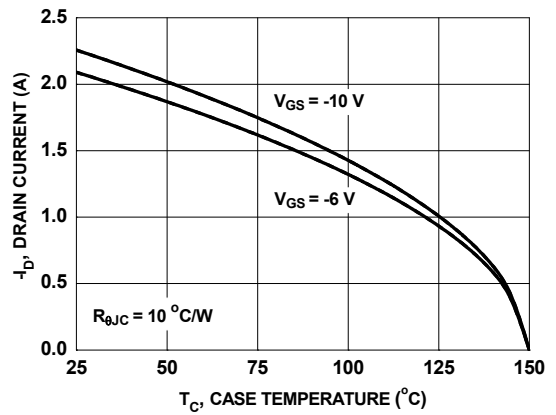


Figure 23. Maximum Continuous Drain Current vs Case Temperature

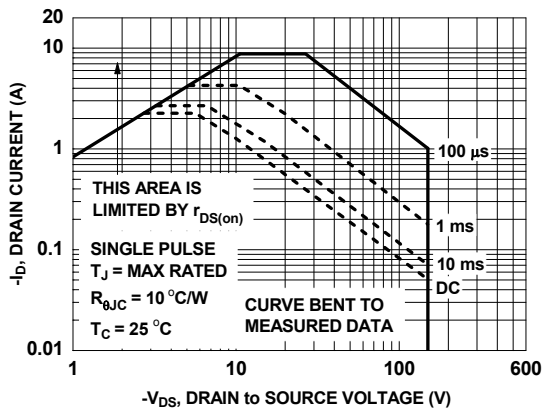


Figure 24. Forward Bias Safe Operating Area

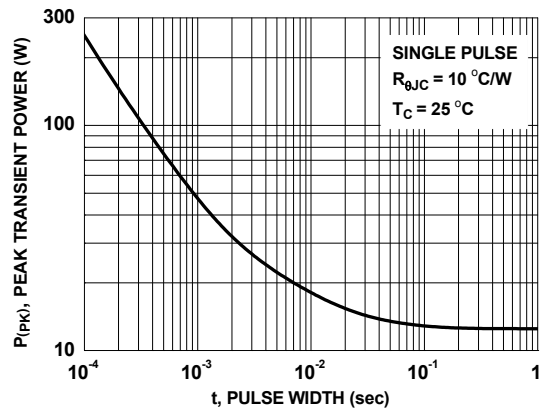


Figure 25. Single Pulse Maximum Power Dissipation

Typical Characteristics (Q2 P-Channel) $T_J = 25^\circ\text{C}$ unless otherwise noted

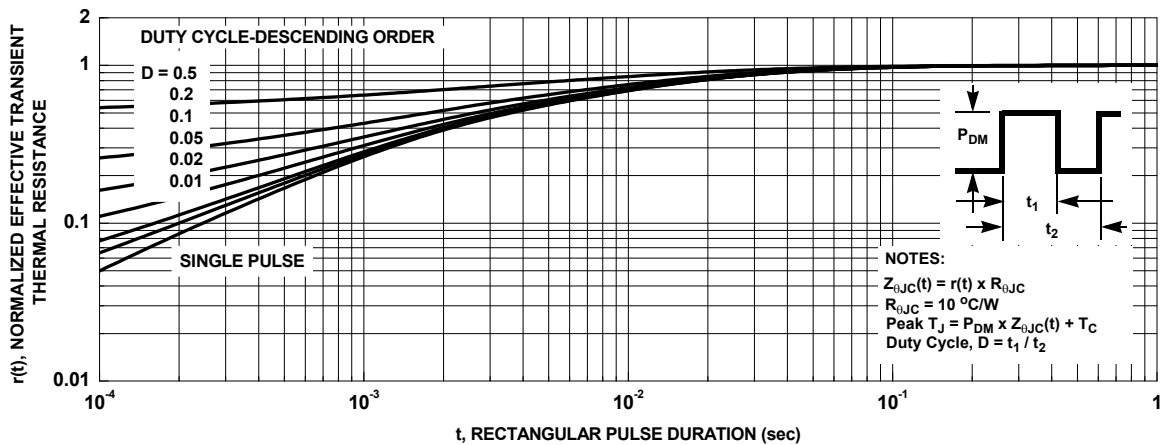
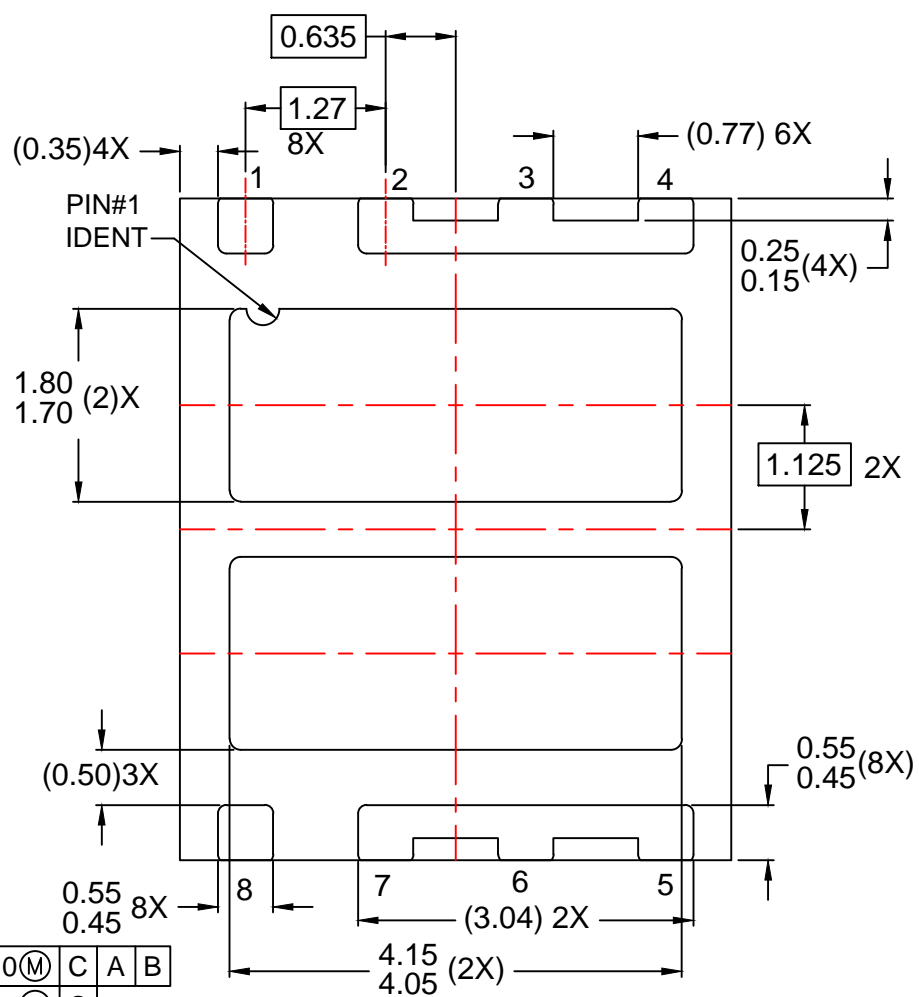
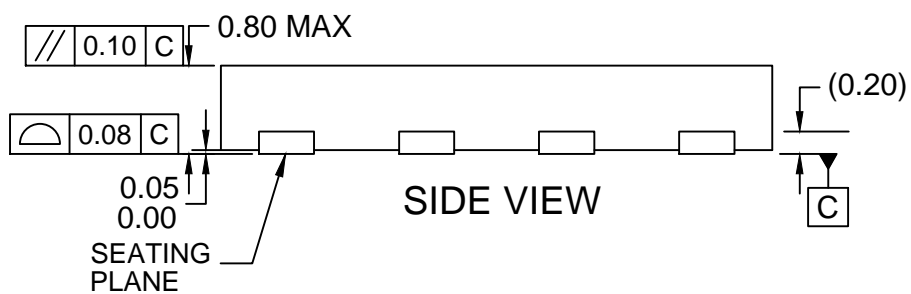
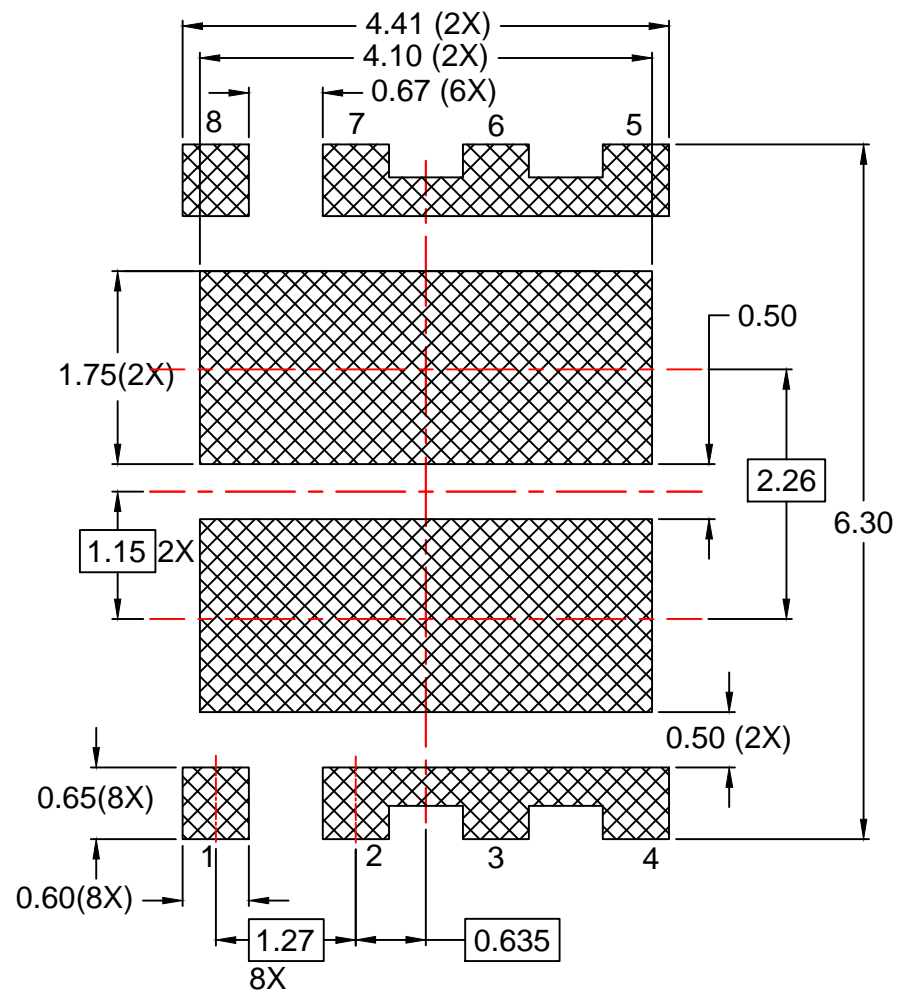
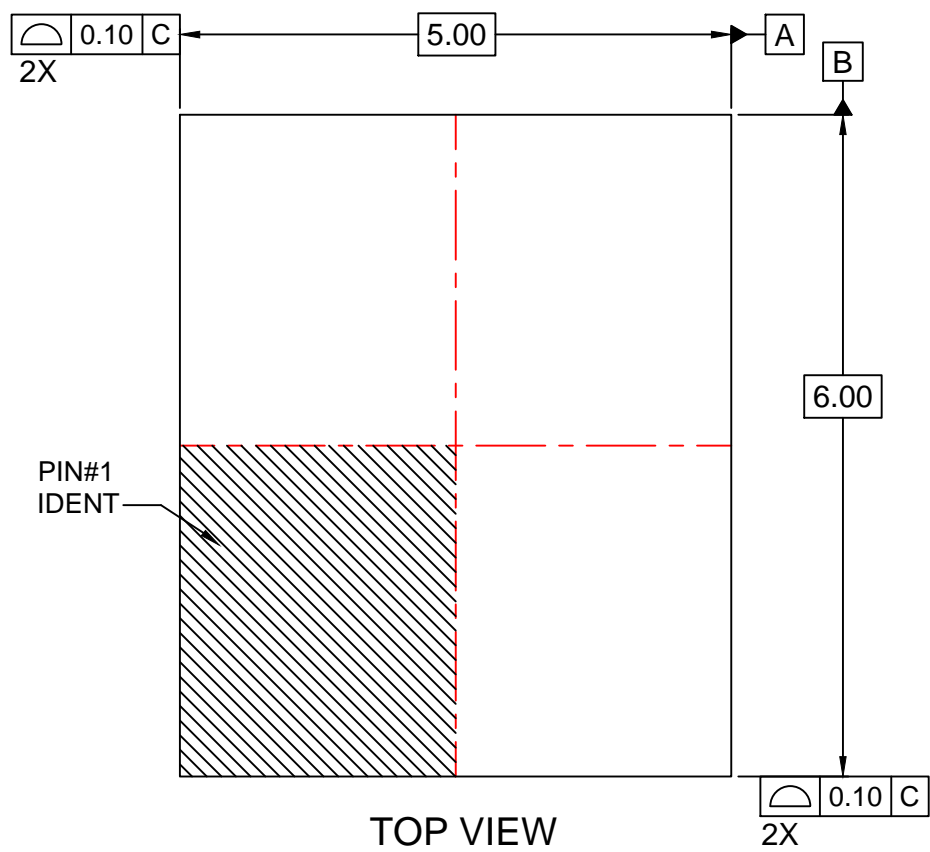


Figure 26. Junction-to-Case Transient Thermal Response Curve



- NOTES:**
- A. DOES NOT FULLY CONFORM TO JEDEC REGISTRATION, MO-229.
 - B. DIMENSIONS ARE IN MILLIMETERS.
 - C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
 - D. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY.
 - E. DRAWING FILENAME: MKT-MLP08Zrev1.

| | | | | |
|---|---------|---|---|---|
| ⊕ | 0.10(M) | C | A | B |
| | 0.05(M) | C | | |



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- FPS™
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- Green FPS™ e-Series™
- Gmax™
- GTO™
- IntelliMAX™
- ISOPLANAR™
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- MegaBuck™
- MICROCOUPLER™
- MicroFET™
- MicroPak™
- MicroPak2™
- MillerDrive™
- MotionMax™
- MotionGrid®
- MTi®
- MTx®
- MVN®
- mWSaver®
- OptoHiT™
- OPTOLOGIC®
- OPTOPLANAR®
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- PowerTrench®
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- Programmable Active Droop™
- QFET®
- QS™
- Quiet Series™
- RapidConfigure™
- ™
- Saving our world, 1mW/W/kW at a time™
- SignalWise™
- SmartMax™
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- SPM®
- STEALTH™
- SuperFET®
- SuperSOT™-3
- SuperSOT™-6
- SuperSOT™-8
- SupreMOS®
- SyncFET™
- Sync-Lock™
- ®
- TinyBoost®
- TinyBuck®
- TinyCalc™
- TinyLogic®
- TINYOPTO™
- TinyPower™
- TinyPWM™
- TinyWire™
- TranSiC™
- TriFault Detect™
- TRUECURRENT®*
- μSerDes™
- ™
- UHC®
- Ultra FRFET™
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